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in line 15, carreel "EP 0 230 336 A1" substitute -- European Patent Application No. 0 230 336-- therefor;

in line 22, cancel "EP" substitute -- European Patent Application No.-- therefor.

On page 2, below line 15, insert a centered heading:

--SUMMARY OF THE INVENTION--;

in line 18, after "The" insert --present--;

cancel lines 21-22, substitute the following at line 21:

This object is achieved in accordance with the present invention in a method for producing a surface mounting optoelectronic component having a base body, an optoelectronic transmitter/receiver that is arranged in a recess of the base body, and an optical device that covers the recess, said method comprising the steps of: preparing the base body with the optoelectronic transmitter/receiver arranged in the recess; filling the recess of the prepared base body with a transparent hardenable casting compound; then placing the optical device onto the as yet uncured casting compound; and then curing the casting compound.

In an embodiment, the step of preparing the base body comprises the steps of: coating a conductor strip with a thermoplast housing while simultaneously forming the recess of the base body into a top surface of the thermoplast housing, a portion of said conductor strip being situated inside the recess; mounting the optoelectronic transmitter/receiver on said portion of the conductor strip situated inside the recess; and filling the recess of the base body with a transparent curable casting compound having thermal characteristics adapted to the thermoplast housing material.

In an embodiment, the recess of the base body is filled with the casting compound to a level such that, during the subsequent placement of the optical device, essentially no casting compound runs over an edge of the recess.

In an embodiment, the recess is filled with casting compound essentially to the edge of the recess such that, after the recess is filled with casting



compound, a fillet develops owing to the surface tension of the casting compound; and the optical device has a shape in a region contacting the casting compound that no casting compound runs over the edge of the recess when the optical device is subsequently placed onto the casting compound.

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In an embodiment, the optical device is placed from above, without pressure, onto one of the base body or at least one seating element attached to said base body within said recess.

In an embodiment, the casting compound is cured by the influence of heat.

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In an embodiment, prior to filling the recess, an optical device is produced by one of casting, pressing, or injection processing; then the optical device is readied and transported as bulk material of optical devices; then a respective optical device is automatically picked from the bulk material; and then the picked optical device is automatically positioned over the base body.

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This object is also achieved in accordance with the present invention in a method for producing a surface mounting optoelectronic component having a base body, an optoelectronic transmitter/receiver that is arranged in a recess of the base body, and an optical device that covers the recess, said method comprising the steps of: preparing the base body with the optoelectronic transmitter/receiver arranged in the recess; then filling the recess of the prepared base body with a first transparent hardenable casting compound; then readying a casting mold half and filling the mold half with a second transparent hardenable casting compound; then at least partially curing at least one of the first casting compound in the recess of the base body and the second casting compound in the mold half; then casting the optical device onto the base body by joining the base body and the mold half properly positioned, such that second casting compound in the mold half comes into contact with a surface of the first casting compound in the recess of the base body; then curing at least one of the second and first casting compound; and then removing the mold half from the base body with the cast-on optical device.

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In an embodiment, the method further comprises, prior to joining the



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base body and the mold half, wetting the surface of the first casting compound.

In an embodiment, the step of wetting the surface of the first casting compound comprises the steps of: turning the base body about a horizontal axis such that an opening of the recess is directed downwardly; and at least superficially immersing the base body in liquid casting compound.

In an embodiment, the at least partial curing of the first casting compound is by heat treatment.

In an embodiment, the at least partial curing of the second casting compound is by heat treatment.

In an embodiment, the method further comprises the steps of: leading a number of base bodies on a first strip; and leading a number of mold halves on a second strip, wherein the first strip and the second strip are led in parallel at least during the step of casting the optical device onto the base body.

In an embodiment, the method further comprises the steps of: leading a number of base bodies on a first strip; combining a number of mold halves in a group; and connecting the group of mold halves, such that they can be detached, to a corresponding number of base bodies at least during the step of casting the optical device onto the base body.

In an embodiment, the base body and the mold half are joined at a temperature of approximately 80°C.

In an embodiment, the second casting compound is cured at a temperature of approximately 150°C.

In an embodiment, the mold half is removed from the base body at a temperature of approximately 80°C.

This object is also achieved in accordance with the present invention in a surface mounting optoelectronic component comprising:

a base body having a thermoplast injection housing and a coated conductor strip secured to the housing, said base body having a recess formed therein with a portion of the conductor strip situated inside the recess;

an optoelectronic transmitter/receiver arranged in the a recess of the base body and mounted on the portion of the conductor strip situated inside the

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recess;

a transparent hardenable casting compound provided in the recess, said casting compound having thermal characteristics adapted to those of the thermoplast housing material; and

an optical device covering the recess and cast onto the casting compound such that a seating surface of the optical device is in surface-wide contact with the casting compound.

In an embodiment, the recess comprises a ring channel surrounding the recess.

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In an embodiment, the base body comprises a number of seating elements for seating of the optical device, said seating elements being arranged at a margin side relative to the recess.--.

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On page 3, in line 9, after "The" insert --present--; in line 12, after "The" insert --present--; in line 18, after "the" insert --present--.

On page 4, in line 4, after "case" insert a comma;

in line 5, after the comma insert --thus--;
in line 15, cancel "depositing [sic]" substitute --placement-- therefor;
in line 16, cancel "In a further advantageous variant of the method"
substitute --In an embodiment-- therefor.

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On page 5, in line 3, preceding "inventive" insert --present--; in line 11, cancel "Lastly" substitute --Last-- therefor; cancel lines 22-29, substitute the following at line 22:

--automation, enabling mass production on an industrial scale.

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These and other features of the invention(s) will become clearer with reference to the following detailed description of the presently preferred embodiments and accompanied drawings.

DESCRIPTION OF THE DRAWINGS

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Figure 1 is a perspective view of a base body with housing and conductor

strip as used in the present inventive method .--. On page 6, in line 1, cancel "Figure 2A,2B,2C" substitute -- Figures 2A, 2B and 2C show-- therefor; in line 4, cancel the semicolon substitute a period therefor; in line 5, after "Figure 3" insert --is--; in line 6, cancel the semicolon substitute a period therefor; in line 7, after "Figure 4" insert --is--; in line 8, cancel the semicolog substitute a period therefor; in line 9, after "Figure 5" insert --shows--; in line 10, cancel the semicolon substitute a period therefor; in line 11, after "Figure 6" insert --is--, and cancel "; and" substitute a period therefor; in line 12, after "Figure 7" insert --is--; below line 13, insert a centered heading: --DETAILED DESCRIPTION OF THE PRESENTLY PREFERRED **EMBODIMENTS**--; in line 24, after "recess" insert --4--. On page 7, in line 11, cancel "2b" substitute --2B-- therefor, and cancel the space before the comma; in line 20, after "housing" insert --3'--, and after "compound" insert --14--; in line 29, after "compound" insert --14--.

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On page 8, in line 6, after "lens" insert --16--, and after "housing" insert -- 3'--;

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in line 7, after "slope" insert --18--; in line 15, after "housing" insert --3'--; in line 16, after "housing's" insert --3'--; in line 18, after "compound" insert --14--.

		On page 9, in line 1, preceding "inventive" insertpresent, and after
		"method" insert a comma;
		in line 7, cancel "mld [sic]" substitutemold therefor;
		in line 13, after "container" insert30
	5	On page 10, in line 9, after "Figure" insert6;
		in line 16, after the first occurrence of "compound" insert14, and after
		the second occurrence of "compound" insert14;
		in line 18, after "compound" insert14;
		in line 22, preceding "inventive" insertpresent;
	10	in line 28, after "effects" insert35
(Co. 42) (Co. 42) (Co. 42) (Co. 42) (Co. 42) (Co. 42)		On page 11, in line 1, after "housing" insert3;
		in line 14, after "treatment" insert43
91 91		
		On page 12, in line 12, cancel "automatization" substituteautomation
		therefor;
	15	below line 12, insert the following paragraph:
		Although modifications and changes may be suggested by those of
DA 3		ordinary skill in the art, it is the intention of the inventors to embody within the

-- Although modifications and changes may be suggested by those of ordinary skill in the art, it is the intention of the inventors to embody within the patent warranted hereon all changes and modifications as reasonably and properly come within the scope of their contribution to the art.--.

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